

## RESPONSE TO OFFICE ACTION

Serial No. 10/616,097

Page 1 of 15

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of: <b>Sun, et al.</b>	§ Case: <b>AMAT/8241/CMP/ECP/RKK</b>
Serial No.: <b>10/616,097</b>	§ Filed: <b>July 8, 2003</b>
Examiner: <b>Edna Wong</b>	§ Group Art Unit: <b>1753</b>
Confirmation No.: <b>1645</b>	§
<b>Title: MULTIPLE-STEP ELECTRODEPOSITION PROCESS FOR DIRECT COPPER PLATING ON BARRIER MATERIALS</b>	§

MAIL STOP Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

## RESPONSE TO OFFICE ACTION DATED MARCH 13, 2008

In response to the Office Action dated March 13, 2008 having a shortened statutory period for response set to expire on June 13, 2008, please enter this response and reconsider the claims pending in the application for the reasons discussed below. Although the Applicants believe that no fee is due in connection with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782 for any other fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.